

REMARKS

This preliminary amendment is filed in order to facilitate processing in the above-identified application. In particular, *Sawada* merely discloses a rubber cover 30 surrounding ferrule 26 and optical fiber 24. Nothing in *Sawada* shows, teaches or suggests an outer peripheral surface being metal plated as claimed in claim 1. Therefore, the combination of *Teruhiro* and *Sawada* does not show, teach or suggest the invention as claimed in claim 1. It is therefore, respectfully requested that the Examiner withdraws the rejection to claims 1, 4-6, 8 and 10-15 under 35 U.S.C. § 103.

Thus, it now appears that the application is in condition for reconsideration and allowance. Reconsideration and allowance at an early date are respectfully requested.

If for any reason the Examiner feels that the application is not now in condition for allowance, it is respectfully requested that the Examiner contact, by telephone, the applicant's undersigned attorney at the indicated telephone number to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed within the currently set shortened statutory period, applicant respectfully petitions for an appropriate extension of time. The fees for such extension of time may be charged to our Deposit Account No. 02-4800.

In the event that any additional fees are due with this paper, please charge our
Deposit Account No. 02-4800.

Respectfully submitted,

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Mark-up of Claim 1

1. (Amended) An electronic apparatus comprising:

an electronic circuit board;

an electrically conductive casing for encasing said electronic circuit board;

a semiconductor element module electrically connected to said electronic circuit board via a plurality of lead terminals, said semiconductor element module having a column-shaped section, an axis of said column-shaped being parallel to a direction of extension of said lead terminals; and

a resin fixture intervening between said electrically conductive casing and said semiconductor element module, said resin fixture mounted with said semiconductor element module and fitted to said electrically conductive casing, said resin fixture having a cylinder-shaped section for retaining, in its inner periphery, said column-shaped section of said semiconductor element module, an outer periphery surface of said cylinder-shaped section being metal plated and an inner periphery surface of said cylinder-shaped section not being metal plated.